Enhanced, high temperature ACTT power switch
6 September 2018 Produ

**Product data sheet** 

## 1. General description

Planar passivated AC Thyristor Triac power switch in a SOT186A (TO-220F) "full pack" plastic package with self-protective capabilities against low and high energy transients. This "series ETN" triac will commutate the full RMS current at the maximum rated junction temperature ( $T_{j(max)}$  = 150 °C) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

#### 2. Features and benefits

- · Clamping structure ensuring safe high over-voltage withstand capability
- High junction operating temperature capability (T<sub>i(max)</sub> = 150 °C)
- High minimum I<sub>GT</sub> for guaranteed immunity to gate noise
- Full cycle AC conduction
- Over-voltage withstand capability to IEC 61000-4-5
- · Pin compatible with standard triacs
- Planar passivated for voltage ruggedness and reliability
- Protective self turn-on capability for high energy transients
- Safe clamping capability for low energy over-voltage transients
- Less sensitive gate for high noise immunity
- Triggering in three quadrants only
- Very high immunity to false turn-on by dV/dt and IEC 61000-4-4 fast transient
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant
- Package meets UL1557 isolation test requirement rated at 2500V RMS

## 3. Applications

- AC pumps and fans
- High power solenoids
- · Highly inductive, resistive and safety loads
- Large and small appliances (White Goods)
- Applications subject to high temperature (T<sub>i(max)</sub> = 150 °C)

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{DRM}$	repetitive peak off- state voltage		-	-	800	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; $T_h \le 134$ °C; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u>	-	-	2	Α

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 20 \text{ ms}$ ; Fig. 4; Fig. 5	-	-	18	Α
		full sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 16.7 \text{ ms}$	-	-	20	Α
Tj	junction temperature		-	-	150	°C
$V_{PP}$	peak pulse voltage	T <sub>j</sub> = 25 °C; non-repetitive, off-state; Fig. 6	-	-	2	kV
Static chara	acteristics		'			
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD+ G+;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	10	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD+ G-;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	10	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD- G-;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	10	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	-	10	mA
$V_{T}$	on-state voltage	I <sub>T</sub> = 3 A; T <sub>j</sub> = 25 °C; <u>Fig. 11</u>	-	-	2	V
$V_{CL}$	clamping voltage	$I_{CL}$ = 0.1 mA; $t_p$ = 1 ms; $T_j$ = 25 °C	850	-	-	V
Dynamic ch	naracteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_{j}$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	500	-	-	V/µs
		$V_{DM}$ = 536 V; $T_j$ = 150 °C; exponential waveform; gate open circuit	200	-	-	V/µs
dl <sub>com</sub> /dt	rate of change of commutating current	$V_D$ = 400 V; $T_j$ = 150 °C; $I_{T(RMS)}$ = 2 A; $dV_{com}/dt$ = 20 V/µs; gate open circuit; snubberless condition	1	-	-	A/ms
		$V_D$ = 400 V; $T_j$ = 150 °C; $I_{T(RMS)}$ = 2 A; $dV_{com}/dt$ = 10 V/µs; gate open circuit	1.5	-	-	A/ms
		$V_D$ = 400 V; $T_j$ = 150 °C; $I_{T(RMS)}$ = 2 A; $dV_{com}/dt$ = 1 V/ $\mu$ s; gate open circuit	3	-	-	A/ms

# **5. Pinning information**

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	СМ	common	mb	Lр
2	LD	load		
3	G	gate		G—/
mb	n.c.	mounting base; isolated	1 2 3 TO-220F (SOT186A)	CM 003aaf296

# 6. Ordering information

#### **Table 3. Ordering information**

Type number		Package	ge general and the second seco				
		Name	Description	Version			
ACT	ΓΤ2X-800ETN	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A			

## 7. Limiting values

## **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	800	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; $T_h \le 134 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	-	2	А
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 20 ms; Fig. 4; Fig. 5	-	18	А
		full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 16.7 ms	-	20	Α
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10 ms; sine-wave pulse	-	1.6	A²s
dl <sub>T</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 20 mA	-	100	A/µs
I <sub>GM</sub>	peak gate current		-	2	Α
$P_{GM}$	peak gate power		-	5	W
P <sub>G(AV)</sub>	average gate power	over any 20 ms period	-	0.5	W
T <sub>stg</sub>	storage temperature		-40	150	°C
Tj	junction temperature		-	150	°C
$V_{PP}$	peak pulse voltage	T <sub>j</sub> = 25 °C; non-repetitive, off-state; <u>Fig. 6</u>	-	2	kV

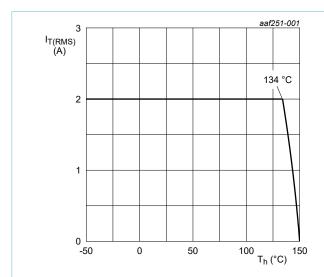


Fig. 1. RMS on-state current as a function of heatsink temperature; maximum values

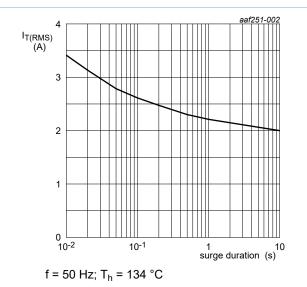


Fig. 2. RMS on-state current as a function of surge duration; maximum values

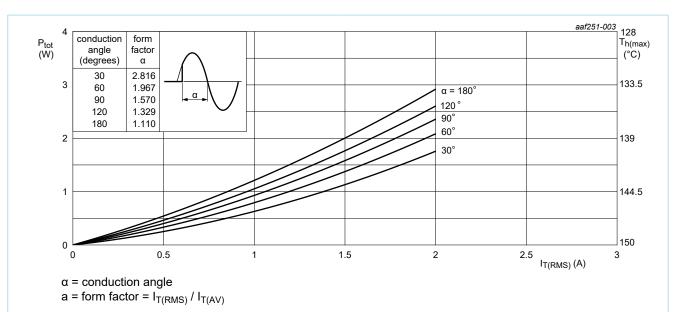


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

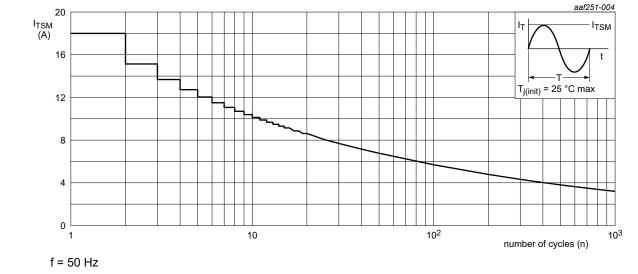


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

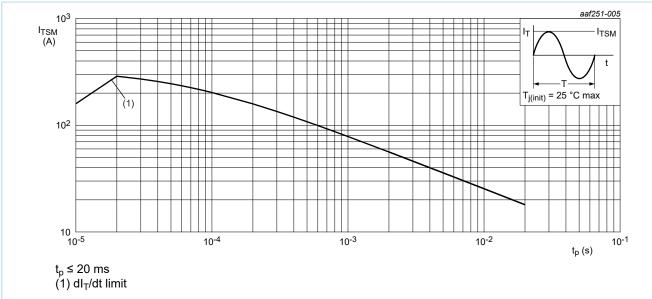


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

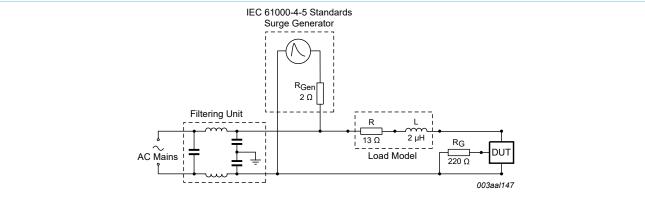
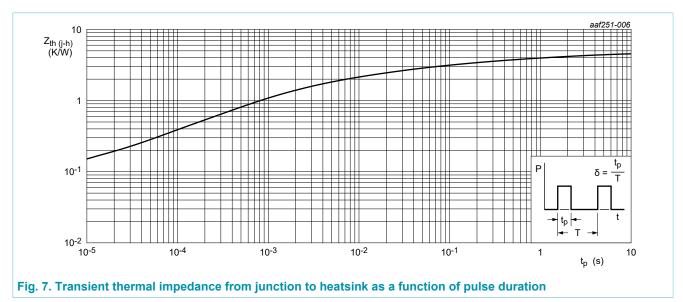


Fig. 6. Test circuit for inductive and resistive loads with conditions equivalent to IEC 61000-4-5

### 8. Thermal characteristics

#### **Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to heatsink	without heatsink compound; Fig. 7	-	-	5.5	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



### 9. Isolation characteristics

#### **Table 6. Isolation characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; $50 \text{ Hz} \le f \le 60 \text{ Hz}$ ; $T_h = 25 ^{\circ}\text{C}$	-	-	2500	V
C <sub>isol</sub>	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; T <sub>h</sub> = 25 °C	-	10	_	pF

## 10. Characteristics

#### Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics					
l <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD+ G+;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	10	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD+ G-;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	10	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD- G-;}$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	10	mA
L	latching current	$V_D = 12 \text{ V; } I_G = 100 \text{ mA; LD+ G+;}$ $T_j = 25 \text{ °C; } Fig. 9$	-	-	25	mA
		$V_D$ = 12 V; $I_G$ = 100 mA; LD+ G-; $T_j$ = 25 °C; Fig. 9	-	-	35	mA
	$V_D = 12 \text{ V}; I_G = 100 \text{ mA}; \text{LD- G-};$ $T_j = 25 \text{ °C}; Fig. 9$	-	-	25	mA	
lн	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 3 A; T <sub>j</sub> = 25 °C; <u>Fig. 11</u>	-	-	2	V
$V_{GT}$	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 100 mA; T <sub>j</sub> = 25 °C; Fig. 12	-	0.8	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 100 mA; T <sub>j</sub> = 150 °C; Fig. 12	0.2	0.5	-	V
D	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C	-	-	2	mA
V <sub>CL</sub>	clamping voltage	$I_{CL}$ = 0.1 mA; $t_p$ = 1 ms; $T_j$ = 25 °C	850	-	-	V
Dynamic cl	naracteristics		1	'	'	
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	500	-	-	V/µs
		V <sub>DM</sub> = 536 V; T <sub>j</sub> = 150 °C; exponential waveform; gate open circuit	200	-	-	V/µs
dl <sub>com</sub> /dt	rate of change of commutating current	$V_D$ = 400 V; $T_j$ = 150 °C; $I_{T(RMS)}$ = 2 A; $dV_{com}/dt$ = 20 V/ $\mu$ s; gate open circuit; snubberless condition	1	-	-	A/ms
		$V_D$ = 400 V; $T_j$ = 150 °C; $I_{T(RMS)}$ = 2 A; $dV_{com}/dt$ = 10 V/ $\mu$ s; gate open circuit	1.5	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150 ^{\circ}\text{C}; I_{T(RMS)} = 2 \text{ A};$ $dV_{com}/dt = 1 \text{ V/}\mu\text{s}; gate open circuit}$	3	-	-	A/ms

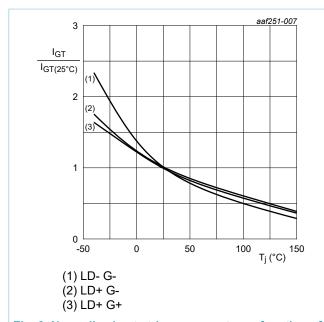


Fig. 8. Normalized gate trigger current as a function of junction temperature

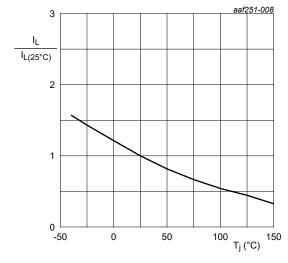


Fig. 9. Normalized latching current as a function of junction temperature

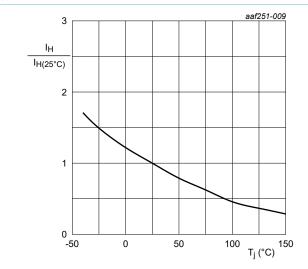
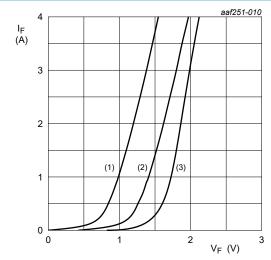


Fig. 10. Normalized holding current as a function of junction temperature



 $V_o$  = 1.066 V;  $R_s$  = 0.2500 Ω (1)  $T_j$  = 150 °C; typical values (2)  $T_j$  = 150 °C; maximum values (3)  $T_j$  = 25 °C; maximum values

Fig. 11. On-state current as a function of on-state voltage

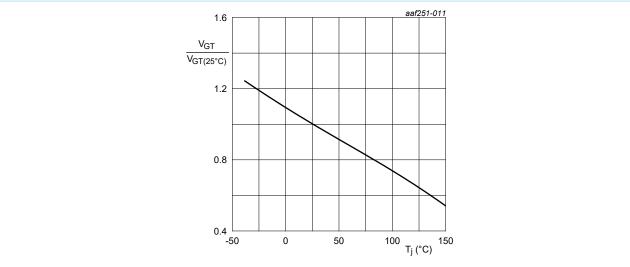


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

## 11. Package outline

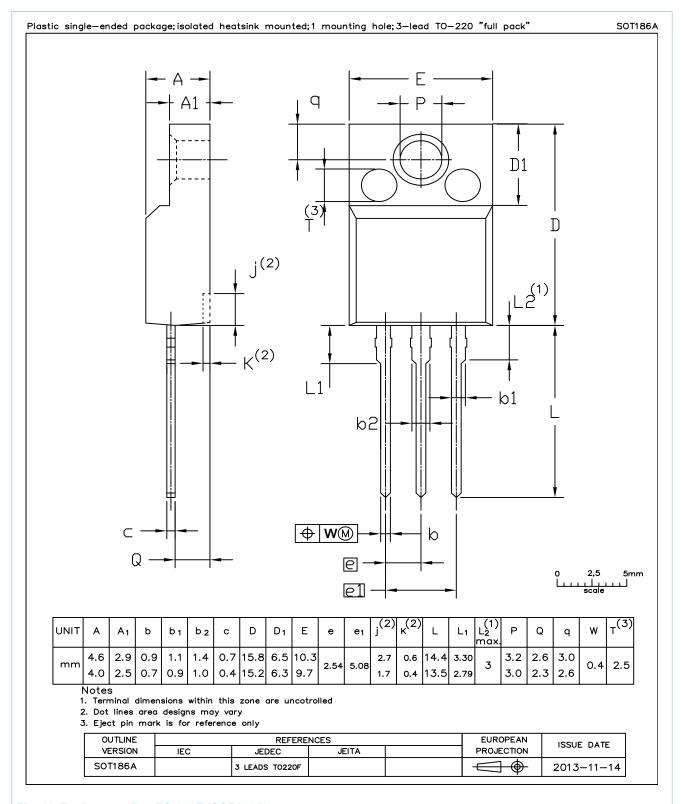


Fig. 13. Package outline TO-220F (SOT186A)

## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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For more information, please visit: http://www.ween-semi.com For sales office addresses, please send an email to: salesaddresses@ween-semi.com Date of release: 6 September 2018

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